

IC402 Series (Open Top) Shrunk Quad Flat Package (2-point Contact Type)

Specifications

Insulation Resistance:	1,000M Ω min. at 100V DC, pitch 0.4, 0.5
	1,000M Ω min. at 500V DC, pitch 0.65, 0.8
Dielec. Withstd. Voltage:	for 1 minute at 100V AC, pitch 0.4, 0.5
	for 1 minute at 500V AC, pitch 0.65
Contact Resistance:	30m Ω max. at 10mA/20mV max.
Operating Temp. Range:	-40°C to +150°C
Contact Force	45g to 20g per pin
Mating Cycles:	5,000 insertions min.

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
Polyethersulphone (PES), glass-filled

Contacts: Beryllium Copper (BeCu)

Plating: Gold over Nickel

Features

- Shrunk socket dimensions for QFP Package
- 2- point contact system

Part Number (Details)

IC402 - 1** 4 - 002 *

Series No.

No. of Contact Pins

Number of Sides
with Contacts

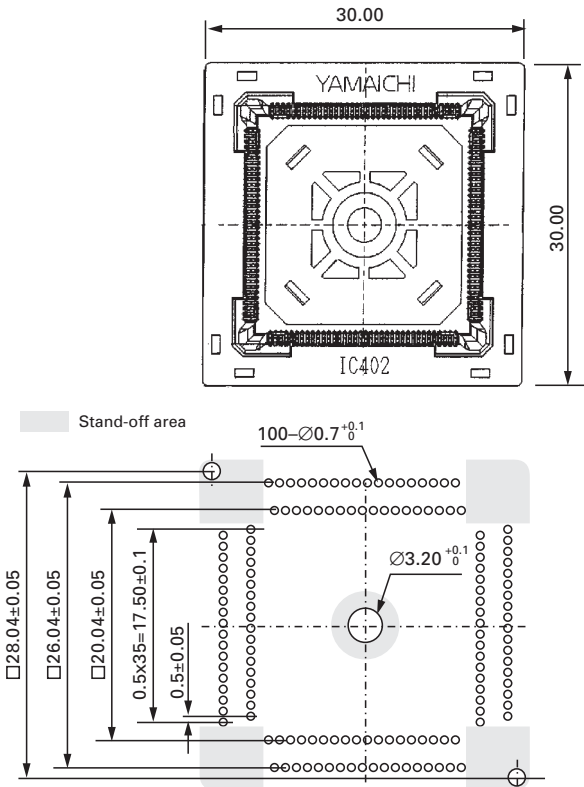
Design Number

Positioning Pin
N = Without Positioning Pin
P = With Positioning Pin



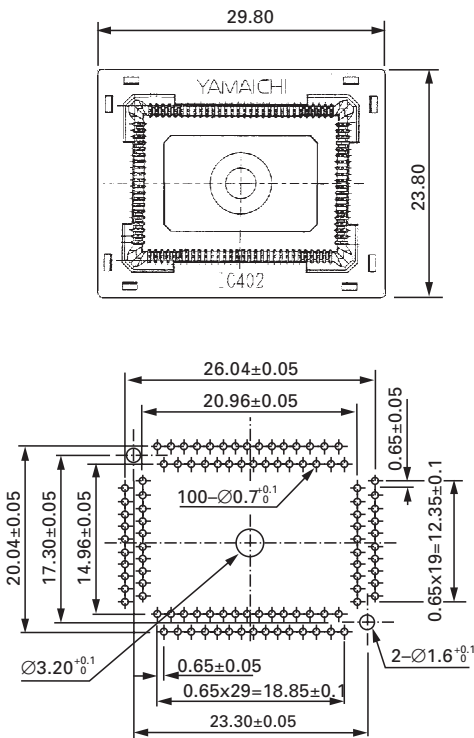
Outline Socket Dimensions and PCB Layout

IC402-1444-003*

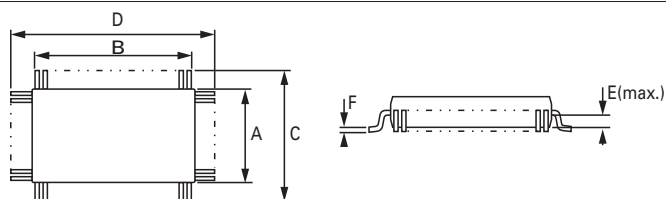


Outline Socket Dimensions and PCB Layout

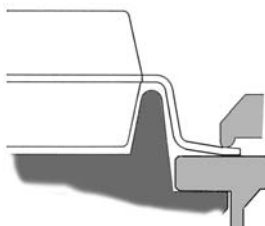
IC402-1004-002*



IC Dimensions



Example of a 2-Point Contact



Part Number	Pin Count	Pitch (mm)	A x B (Body)	C	D	E (max)	F
IC402-1004-002*	100	0.5	14.0 x 20.0	16.0	22.0	0.7	0.127
IC402-1444-003*	144	0.5	20.0 x 20.0	22.0	22.0	0.8	0.145